



Electronic Filing System (EFS) Data

Electronic Patent Application Submission

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EFS ID: 57195
Application ID: 10686486 
Title of Invention: APPARATUS FOR ELECTRO
CHEMICAL DEPOSITION OF
COPPER METALLIZATION WITH
THE CAPABILITY OF IN-SITU
THERMAL ANNEALING
First Named Inventor: ROBIN CHEUNG
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-10-15
Effective Receipt Date: 2004-03-16
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 8014
Attorney Docket Number: AMAT3421C2
Total Fees Authorized: 180.0
Payment Category: Deposit Account
Deposit Account Number: 200782
Deposit Account Name: N. Alexander Nolte
Access Code: ****
RAM Payment Status: RAM success
RAM User ID: EFSPROD
RAM Accounting Date: 2004-03-16
RAM Sequence Number: 16

Digital Certificate Holder: cn=N. Alexander Nolte,ou=Registered Attorneys,ou=Patent and
Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US
Certificate Message Digest: 79a2cccee8464255fb08817a8b9cb2d835a59d05



TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING	
Application Number:	10/686486	
Date:	2003-10-15	
First Named Applicant:	ROBIN CHEUNG	
Confirmation Number:	8014	
Attorney Docket Number:	AMAT3421C2	
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Submitted by:	Elec. Sign.	Sign. Capacity
Mr. N. ALEXANDER NOLTE Registered Number: 45689	[N. ALEXANDER NOLTE]	Attorney
Documents being submitted	Files	
us-fee-sheet	AMAT3421C2NAN3-usfees.xml	
	us-fee-sheet.xsl	
	us-fee-sheet.dtd	
us-ids	AMAT3421C2NAN3-usidst.xml	
	us-ids.dtd	
	us-ids.xsl	



Comments

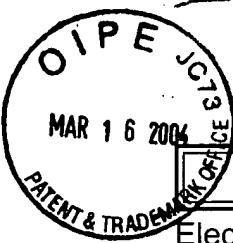


FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING										
Application Number:	10/686486										
Date:	2003-10-15										
First Named Applicant:	ROBIN CHEUNG										
Attorney Docket Number:	AMAT3421C2										
Art Unit:	1753										
TOTAL FEE AUTHORIZED \$180											
Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
Fee Description	Fee Code	Amount \$	Fee Paid \$								
Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Deposit account number: 200782											
Access Code	*****										
Deposit name:	Moser Patterson Sheridan										
Deposit authorized name:	N. Alexander Nolte										
Signature:	/N. Alexander Nolte/										
Date (YYYYMMDD):	2004-03-16										



FEE TRANSMITTAL

Electronic Version v08
Stylesheet Version v08.0

Title of Invention	APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING		
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Deposit authorized name:	N. Alexander Nolte		
Signature:	/N. Alexander Nolte/		
Date (YYYYMMDD):	2004-03-16		



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	APPARATUS FOR ELECTRO CHEMICAL DEPOSITION OF COPPER METALLIZATION WITH THE CAPABILITY OF IN-SITU THERMAL ANNEALING
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Application Number: 10/686486



Confirmation Number: 8014

First Named Applicant: ROBIN CHEUNG

Attorney Docket Number: AMAT3421C2

Art Unit: 1753

Search string: (2026605 or 4265943 or 4786337 or 5156731
or 5384284 or 5510216 or 5846598 or 5885749
or 5891513 or 5907790 or 5913147 or 5994675
or 6017777 or 6030208 or 6037257 or 6171922
or 6174388 or 6207937 or 6211495 or 6222164
or 6242349 or 6258223 or 6290833 or 6296906
or 6483081 or 6544338 or 5431700 or 6072163
or 6307184 or 6423947 or 6529686 or 6639189
or 20020004301 or 20020102837 or
20030045095).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	2026605	1936-01-07	ANTISELL			
	2	4265943	1981-05-05	GOLDSTEIN, ET AL.			
	3	4786337	1988-11-22	MARTIN			
	4	5156731	1992-10-20	OGASAWARA, ET AL.			
	5	5384284	1995-01-24	DOAN, ET AL.			
	6	5510216	1996-04-23	CALABRESE, ET AL.			
	7	5846598	1998-12-08	SEMKOW, ET AL.			
	8	5885749	1999-03-23	HUGGINS, ET AL.			
	9	5891513	1999-04-06	DUBIN, ET AL.			
	10	5907790	1999-05-25	KELLAM			
	11	5913147	1999-06-15	DUBIN, ET AL.			



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13	6017777	2000-01-25	KIM, ET AL.
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27	5431700	1995-07-11	SLOAN
28	6072163	2000-06-06	ARMSTRONG, ET AL.
29	6307184	2001-10-23	WOMACK, ET AL.
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31	6529686	2003-03-04	RAMANAN, ET AL.
32	6639189	2003-10-28	RAMANAN, ET AL.

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020004301	2002-01-10	CHEN, ET AL.			
	2	20020102837	2002-08-01	RITZDORF, ET AL.			
	3	20030045095	2003-03-06	RITZDORF, ET AL.			

Signature

Examiner Name	Date